

### **General Description**

The WSF70N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF70N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

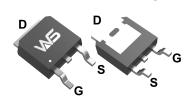
### **Product Summery**

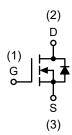
BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>		
100V	10mΩ	70A		

### **Applications**

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

### **TO-252-2L Pin Configuration**





### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	±25	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	70	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	35	Α
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	8.2	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	6.6	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2,</sup> T <sub>C</sub> =25°C	150	Α
EAS	Avalanche Energy, Single pulse,L=0.5mH	169	mJ
I <sub>AS</sub>	Avalanche Current, Single pulse,L=0.5mH	26	Α
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation⁴	113	W
P <sub>D</sub> @T <sub>C</sub> =100°C	Total Power Dissipation <sup>4</sup>	45	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

#### **Thermal Data**

Symbol	Parameter		Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		1.1	°C/W



### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.096		V/℃	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		10	13	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/   -250A	2.0	3.0	4.0	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.5		mV/℃	
	Drain Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =25 $^{\circ}$ C			1		
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			5	· uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		27		S	
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0	1.8	Ω	
$Q_g$	Total Gate Charge (10V)			42			
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =80V , V <sub>GS</sub> =10V , I <sub>D</sub> =30A		12		nC	
$Q_gd$	Gate-Drain Charge			12			
T <sub>d(on)</sub>	Turn-On Delay Time			9			
Tr	Rise Time	$V_{DD}$ =50V , $V_{GS}$ =10V , $R_G$ =3 $\Omega$ ,		19		no	
$T_{d(off)}$	Turn-Off Delay Time	I <sub>D</sub> =1A		22		ns	
T <sub>f</sub>	Fall Time			36			
C <sub>iss</sub>	Input Capacitance			2100			
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		255		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			100			

### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.5mH , I <sub>AS</sub> =26A	150			mJ

### **Diode Characteristics**

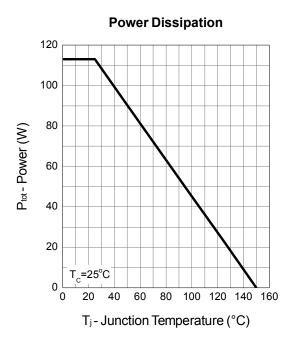
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	V =V =0V Force Current			30	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			60	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =15A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I= 450 dI/dt 4000 / T 05°C		42		nS
Qrr	Reverse Recovery Charge	IF=15A,dI/dt=100A/µs,T <sub>J</sub> =25℃		90		nC

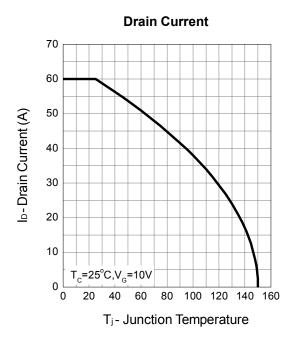
#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DS}$ =25V, $V_{GS}$ =10V,L=0.5mH, $I_{AS}$ =26A
- 4.The power dissipation is limited by 150  $^{\circ}\mathrm{C}\,$  junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

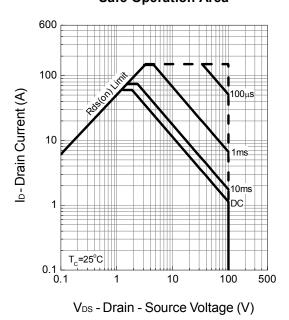


### **Typical Operating Characteristics**

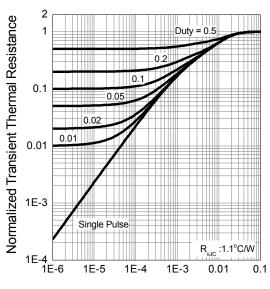




### **Safe Operation Area**



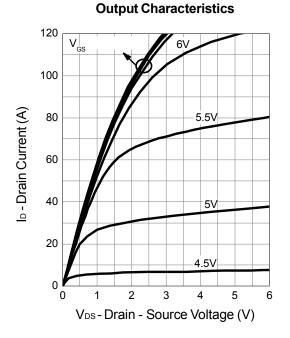
### **Thermal Transient Impedance**



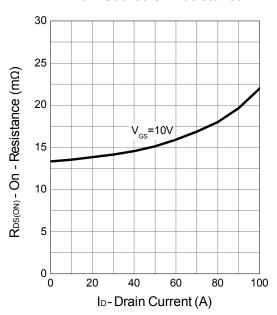
Square Wave Pulse Duration (sec)



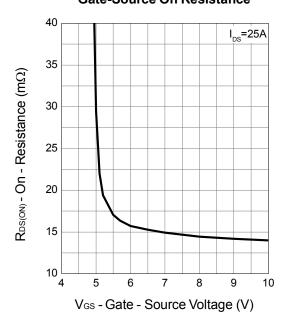
## **Typical Operating Characteristics (Cont.)**



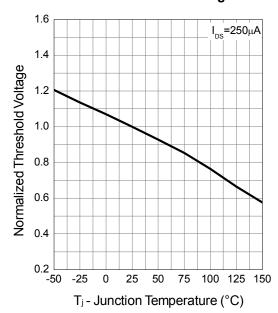
#### **Drain-Source On Resistance**



### **Gate-Source On Resistance**



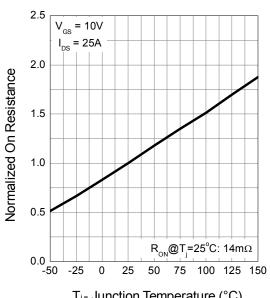
### **Gate Threshold Voltage**



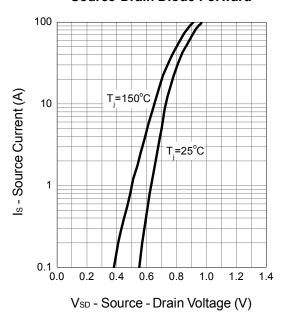


### Typical Operating Characteristics (Cont.)

# **Drain-Source On Resistance**

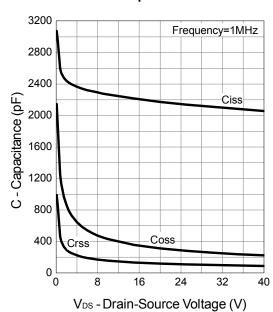


#### Source-Drain Diode Forward

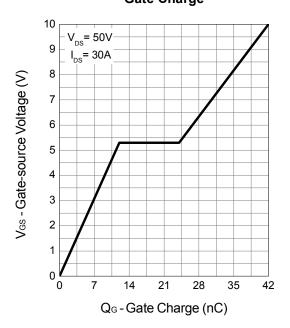


T<sub>j</sub>- Junction Temperature (°C)

#### Capacitance

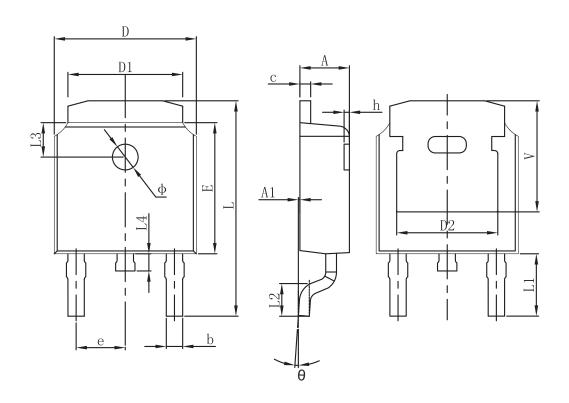


### **Gate Charge**





## **Packaging information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.635	0.770	0.025	0.030	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	REF.	0.190	REF.	
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.712	10.312	0.382	0.406	
L1	2.900 REF.		0.114	REF.	
L2	1.400	1.700	0.055	0.067	
L3	1.600 REF.		0.063	REF.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.250	REF.	0.207 REF.		



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